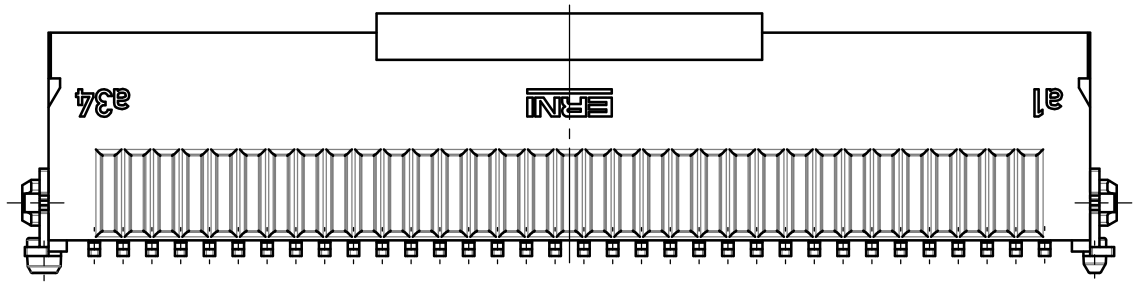
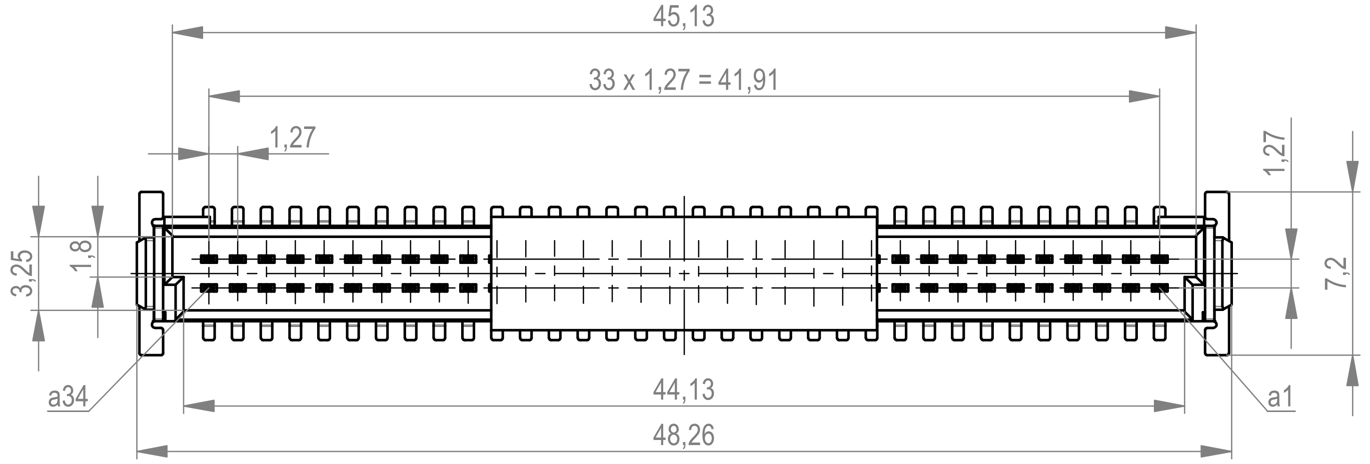
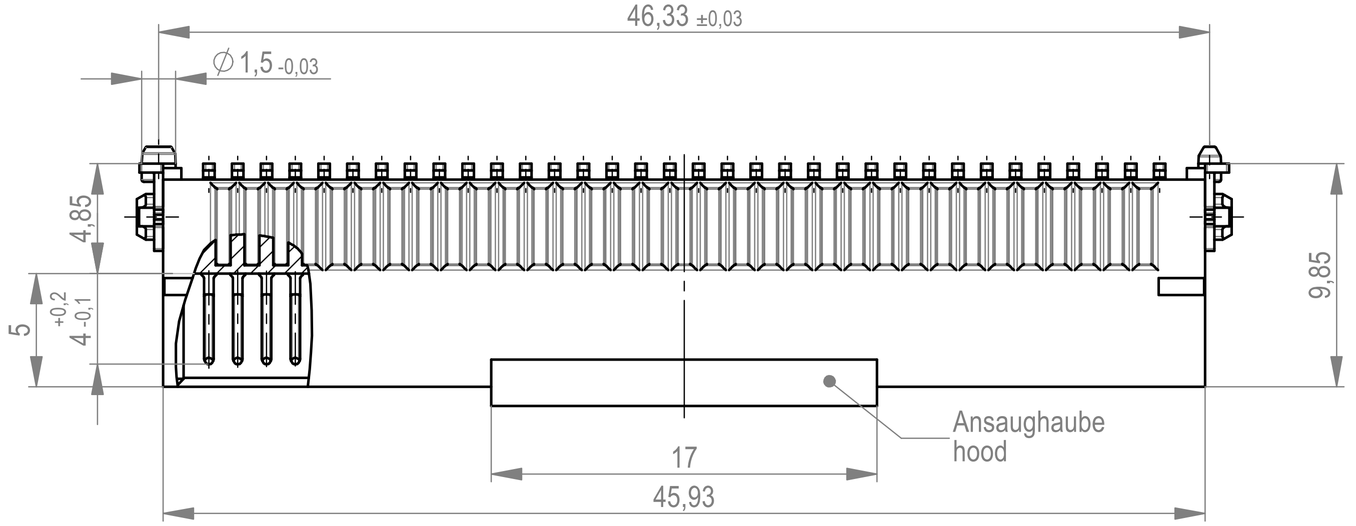
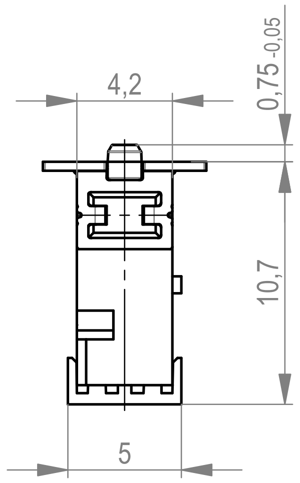


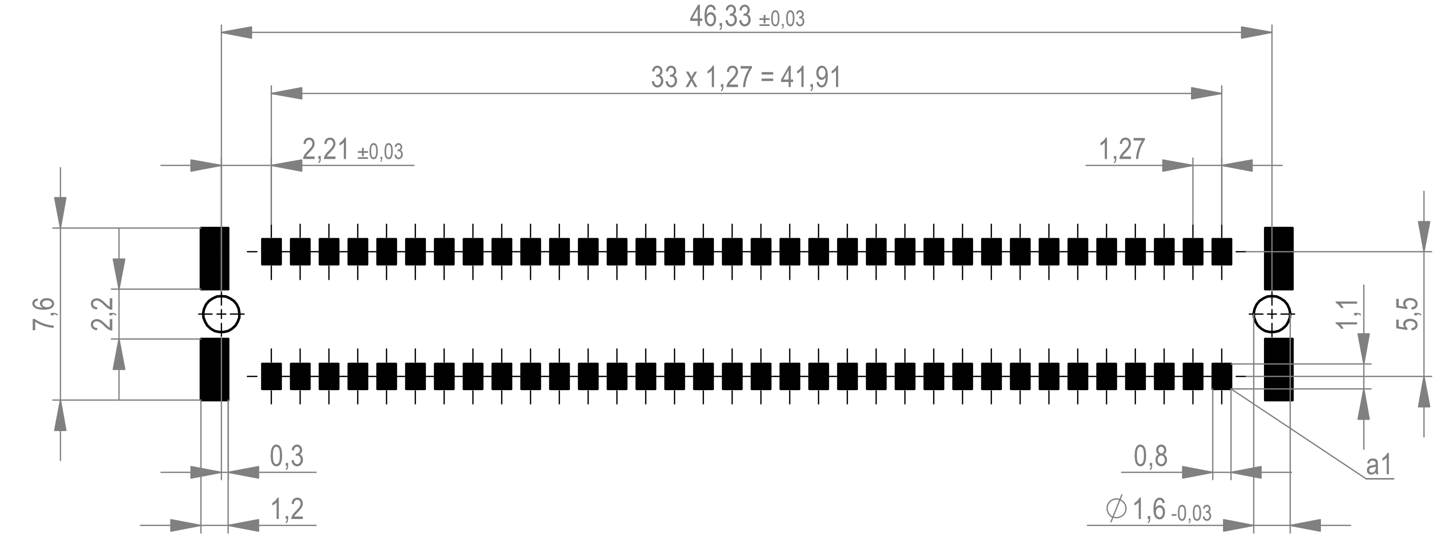






Leiterplatten-Layout Vorschlag für SMT

PCB-Layout Proposal for SMT



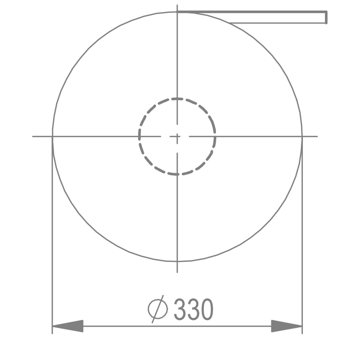
Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
tape on reel packaging according to DIN IEC 60286-3
Verpackungseinheit: 240 Stück
packaging unit: 240 pcs

Anforderungsstufe 1
performance level 1

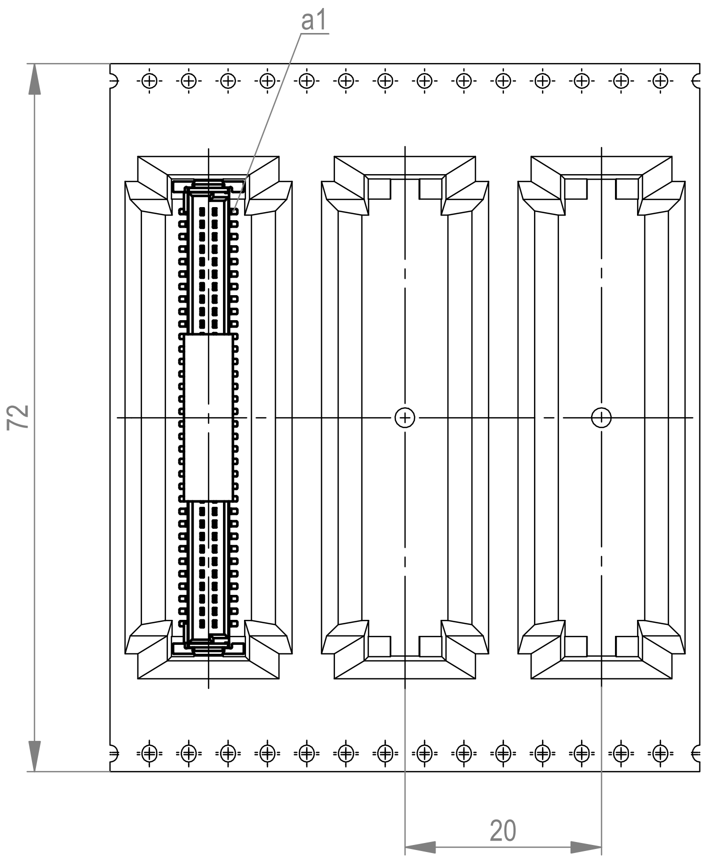
Kontaktbereich vergoldet
mating area gold plating

Anschlussbereich verzinnt 4-6 µm
terminal area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
coplanarity area of termination ≤ 0,1 mm



Abspulrichtung - *reel off direction*



BA 8-23 hohe Bauhöhe
type 8-23 High Profile

Dimension no.

Tolerances
ISO 8015

All Dimensions in mm

Scale 3:1
Material

Customer drawing:
This Drawing is a controlled Document.

Subject to modification without prior notice.
Drawing will not be updated.

Messerl. SMC-Q 68-SMD-BA8-23
Male SMC-Q 68-SMD-type8-23

TE Connectivity

C-234209-E

C
A3

Index	Date
f1	12.05.2023

Class SMCQ

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